

U.S. Department of Commerce, Patent and Trademark Office	Docket No.	Serial No.
	APPM/1931	08/856,116
LIST OF RELEVANT ART CITED BY APPLICANT		Applicant
(Use several sheets if necessary)		Fusen Chen et al.
		Filing Date
		May 14, 1997
U.S. Patent Documents		

*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
BES	AA	5,308,793	05/03/1994	TAGUCHI ET AL.			
BES	AB	5,371,042	12/06/1994	ONG			RECEIVED
BES	AC	5,486,492	01/23/1996	YAMAMOTO ET AL.			APR 1 1999
	AD						GROUP 1700
	AE						
	AF						
	AG						
	AH						RECEIVED
	AI						NOV 25 1999 RECEIVED
	AJ						GROUP 2100 - 07 0999
	AK						

Foreign Patent Documents

Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
BES	AL	08213119	07-24-1996	JAPAN (Abstract)			X	
	AM							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AQ	PCT Notification of Transmittal of The International Search Report or the Declaration and PCT International Search Report				
AR	Donald S. Gardner, Jin Onuki, Kazue Kudoo, Yutaka Misawa, Quat T. Vu, "Encapsulated copper interconnection devices using sidewall barriers, 1995, pages 104-119				
AT	Si-Yeoul Jang, Sung-Man Lee "Tantalum and niobium as a diffusion barrier between copper and silicon," 1996, pages 271-278				
AS	Tadashi Iijima, Yoshiakai Shimooka, and Kyoichi Suguro, "An Amorphous Ti-Si-N Diffusion Barrier Layer for Cu Interconnections," Vol. 78, No. 12, 1995, pages 67-74				

Examiner Bernard E. Soule Date Considered 7/2/99

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

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Applicant

Liang-Yuh Chen, Fusen Chen, Moshe Eizenberg, and Roderick Craig Mosely

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AA						
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BES	AN	K. Mikagi, H. Ishikawa, T. Usami, M. Suzuki, K. Inoue, N. Oda, S. Chikaki, I. Sakai and T. Kikkawa, "Barrier Metal Free Copper Damascene Interconnection Technology Using Atmospheric Copper Reflow and Nitrogen Doping in SiOF Film," 1996 IEEE, pp. 365-368
BES	AO	Y. Shacham-Diamand, V. Dubin and M. Anyal, "Electroless Copper Deposition for ULSI," 1995 Elsevier Science S.A., pp. 93-103
BES	AP	Electromigration and Diffusion in Pure Cu and Cu(Sn) Alloys, C.-K. Hu, K. L. Lee, D. Gupta, and P. Blauner, Mat. Res. Soc. Symp. Vol 427, (96-105)

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	AN							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>BES</i>	AO	Electromigration Failure Distributions for Multi-Large Interconnects as a Function of Line Width: Experiments and Simulation, D.D. Brown, J.E. Sanchez, Jr., V. Pham, P.R. Besser, M.A. Korhonen, and C.-Y. Li, Mat. Res. Soc. Symp. Vol 427
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	AQ	

Examiner *Bernard E. Souw*Date Considered *07/02/99*

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